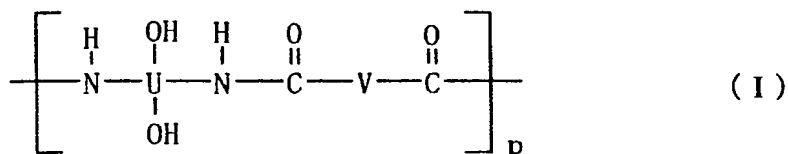


CLAIMS

1. A photosensitive polymer composition comprising:

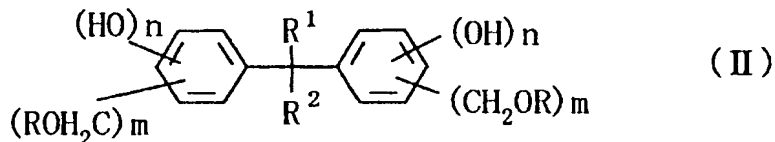
(a) a polyamide having a repeating unit represented by
5 the following general formula (I):



wherein U represents a tetravalent organic group, V represents a bivalent organic group and p is an integer representing a number of the repeating unit;

10 (b) a compound which generates an acid upon receiving light; and

(c) a compound represented by the following general formula (II):



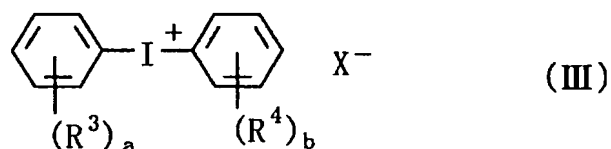
15 wherein m and n are each independently integer of 1 or 2, Rs are each independently hydrogen, alkyl group or acyl group, and R¹ and R² each independently represents fluoroalkyl group having 1 to 3 carbon atoms.

20 2. The photosensitive polymer composition according to claim 1, wherein the compound represented by the general formula (II) is 2,2-bis[3,5-bis(hydroxymethyl)-4-hydroxyphenyl]-1,1,1,3,3,3-hexafluoropropane.

25 3. The photosensitive polymer composition according to claim 1, wherein the compound represented by the general

formula (II) is 2,2-bis[3,5-bis(methoxymethyl)-4-hydroxyphenyl]-1,1,1,3,3,3-hexafluoropropane.

4. The photosensitive polymer composition according to any one of claims 1 to 3, wherein ratios of the component (b) and the component (c) are 5 to 100 parts by weight and 1 to 30 parts by weight, respectively based on 100 parts by weight of the component (a).
5. The photosensitive polymer composition according to any one of claims 1 to 3 further comprising (d) a compound which reduces a solubility of the component (a) with respect to an alkali aqueous solution.
6. The photosensitive polymer composition according to claim 5, wherein the component (d) is a diaryliodonium salt represented by the following general formula (III):



- wherein X^- represents counteranion, R^3 and R^4 each independently represents alkyl group or alkenyl group, and a and b are each independently integer of 0 to 5.

7. The photosensitive polymer composition according to claim 5, wherein ratios of the component (b), the component (c) and the component (d) are 5 to 100 parts by weight, 1 to 30 parts by weight and 0.01 to 15 parts by weight, respectively based on 100 parts by weight of the component (a).
8. A method of producing a pattern comprising the steps

of:

applying the photosensitive polymer composition
according to any one of claims 1 to 3 on a support
substrate and drying the photosensitive polymer
5 composition;

exposing light to a photosensitive resin layer
obtained by drying the photosensitive polymer composition
to make a predetermined pattern;

developing the photosensitive resin layer after the
10 exposing light; and

heat treating the photosensitive resin layer after the
developing.

9. The method of producing the pattern according to claim
15 8, wherein an exposure light source used in the step of
exposing generates i-line.

10. An electronic part comprising:
an electronic device having a layer of the pattern
20 obtained by the method according to claim 8,
wherein the layer of the pattern is provided as an
interlayer insulating film and/or a surface protection
layer in the electronic device.